



Material Content Data Sheet



Sales Product Name		ESD217-B1-02EL E6327		Issued		20. July 2018		
MA#		MA001230272						
Package		PG-TSLP-2-19		Weight*		0.61 mg		
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	non noble metal	tin	7440-31-5	0.001	0.09		885	
	noble metal	gold	7440-57-5	0.002	0.34		3435	
	inorganic material	silicon	7440-21-3	0.026	4.19	4.62	41926	46246
leadframe	non noble metal	nickel	7440-02-0	0.241	39.44	39.44	394393	394393
wire	non noble metal	copper	7440-50-8	0.003	0.42	0.42	4243	4243
encapsulation	organic material	carbon black	1333-86-4	0.002	0.26		2579	
	plastics	epoxy resin	-	0.046	7.48		74769	
	inorganic material	silicondioxide	60676-86-0	0.267	43.83	51.57	438302	515650
leadfinish	noble metal	gold	7440-57-5	0.010	1.71	1.71	17078	17078
plating	noble metal	palladium	7440-05-3	0.003	0.53		5312	
	noble metal	gold	7440-57-5	0.010	1.71	2.24	17078	22390
*deviation	< 10%		Sum in total:			100.00		1000000

Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
2. Infineon Technologies AG and Infineon Technologies AG suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.
3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and does not use any exemption

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